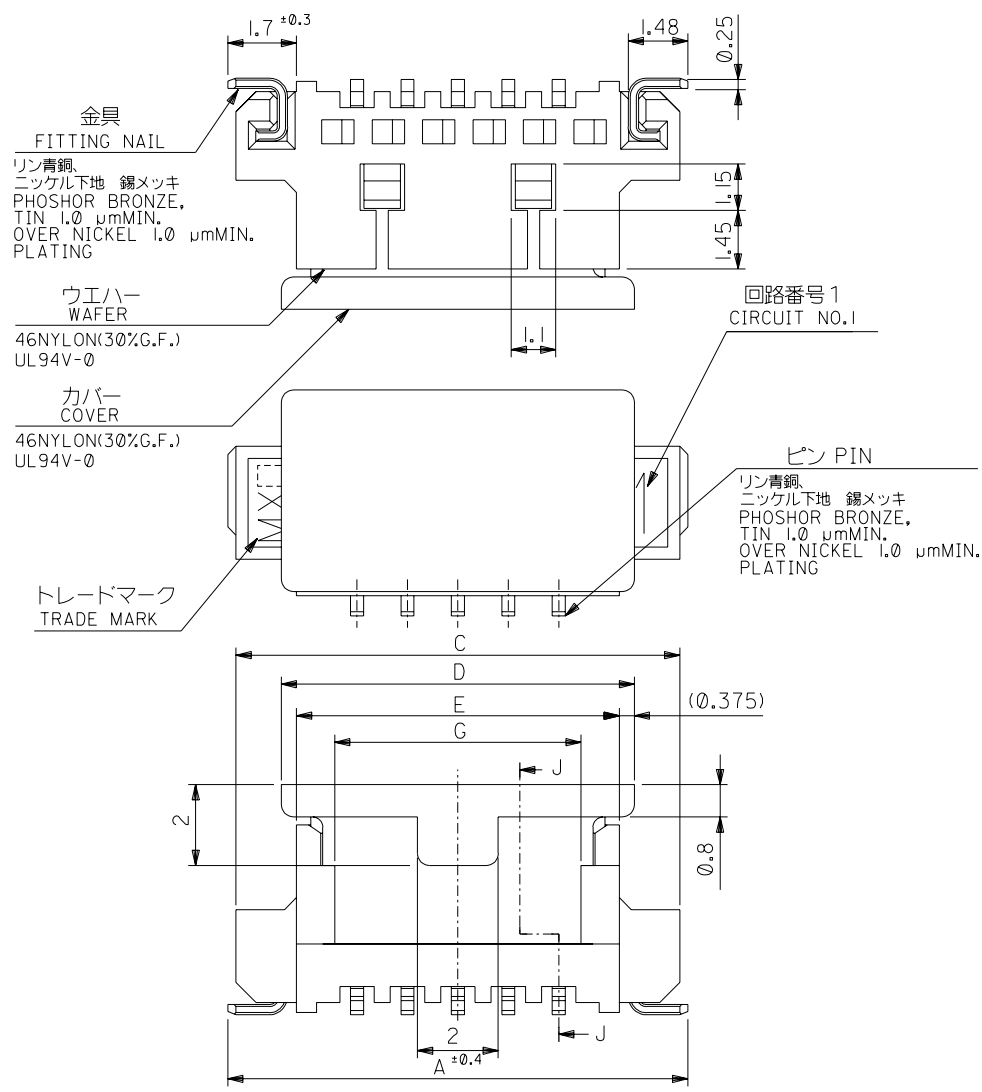
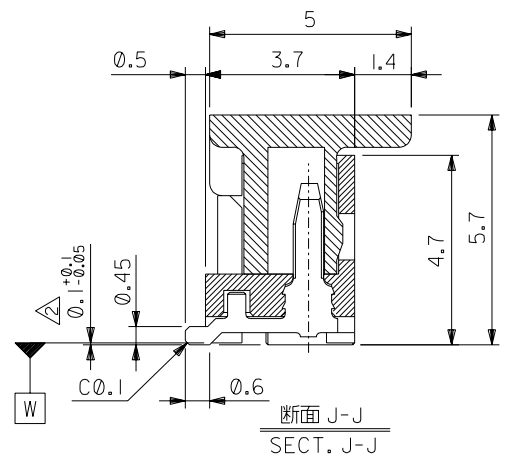


DWG. NO.
SD-53398-034



NOTES

1. 嵌合相手: 51021シリーズ MATE WITH: 51021 SERIES
2. 水平面上においての、ウエハー底面 [W] とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
3. 偶数極のみ適用。 APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



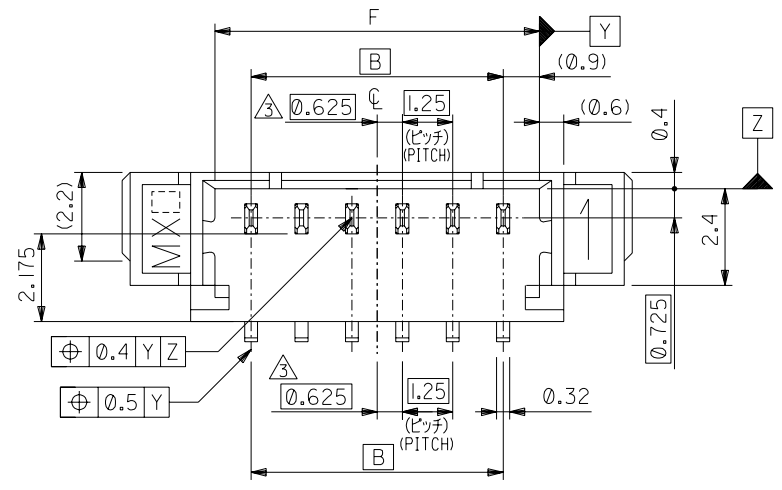
17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DO NOT SCALE DRAWING

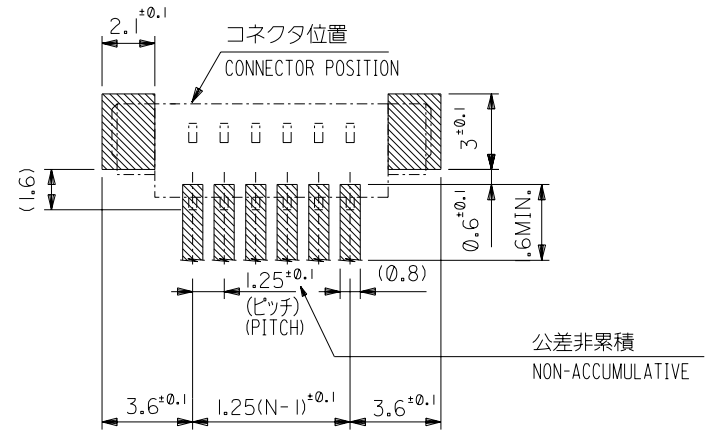
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO RELEASED '04/02/12	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	MODEL NO. 53398-**29	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
						FINISH 仕上げ #	10 UNDER 未満 ±0.2 10 OVER 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3	DRAWN BY & DATE Y.SAKIYAMA '04/02/12 CHECKED BY & DATE M.SASAO '04/02/12 APPROVED BY & DATE M.SASAO '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
						WIRE RANGE 適用電線範囲 #	ANGLE 角度 ±3°	CAD FILENAME SD-53398-034.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 1 OF 2
						INS. RANGE 被覆外径 #	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			SIZE B	

SD-53398-034.S01

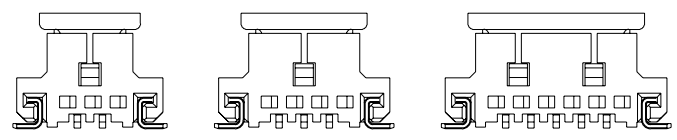
8 7 6 5 4 3 2 1



カバーなしの場合 (53398-**19)
IN CASE OF WITHOUT COVER



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



ロック形状図
LOCK CONFIGURATION

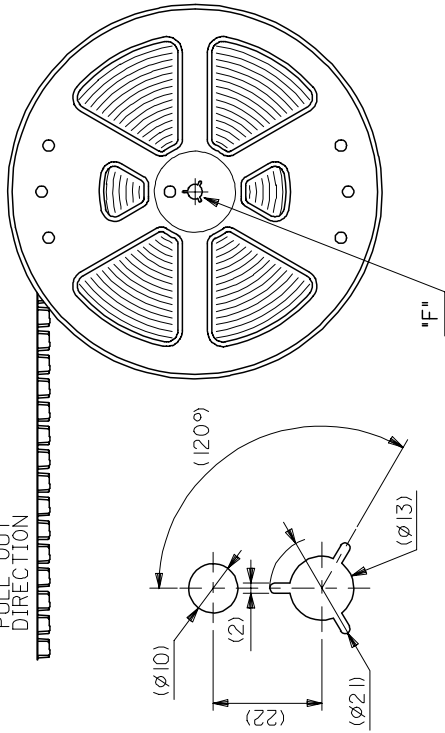
NOTES

△ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

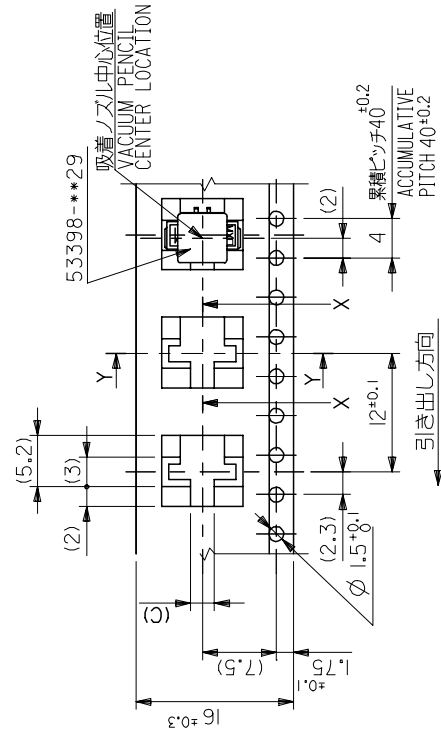
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	MODEL NO.	53398-**29	DIMENSIONS:	SHT	REV
							SEE NOTES	10 UNDER 未満	10 OVER 以上 30 UNDER 未満	30 OVER 以上	ANGLE 角度	DESIGN UNITS mm □ INCH	THIRD ANGLE PROJECTION	mm □ INCH
						FINISH 仕上げ			DRAWN BY & DATE Y.SAKIYAMA '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-				
						WIRE RANGE 適用電線範囲			CHECKED BY & DATE M.SASAO '04/02/12	MOLEX INCORPORATED				
						INS. RANGE 被覆外径			APPROVED BY & DATE M.SASAO '04/02/12	CAD FILENAME SD-53398-034.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										SIZE B	EN-02J(097) MXJ-54			

8 7 6 5 4 3 2 1

引き出し方向
PULL OUT
DIRECTION

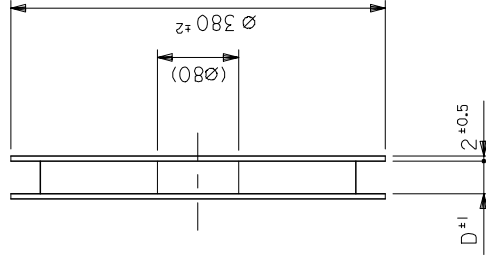


DETAIL "F"

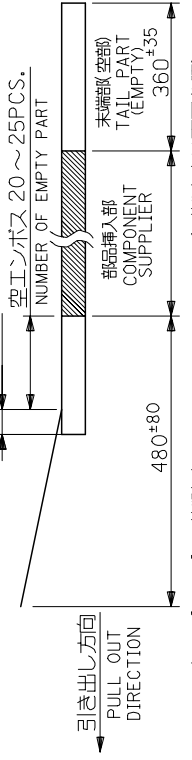


引き出し方向
PULL OUT DIRECTION

16幅テープ
(TAPE WIDTH:16)



- NOTES
- 梱包数量: 1,000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
 - リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

<剥離速度: 300mm/min (参考)>
PEELING SPEED: 300mm/min.
(REFERENCE)

10°
剥離方向
PEEL OFF
DIRECTION

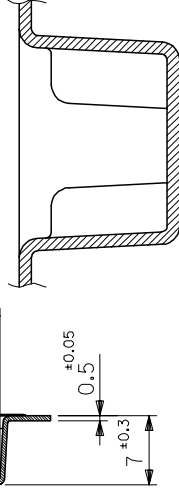
引き出し方向
PULL OUT
DIRECTION

- 53398-***29の詳細寸法については図面 SD-53398-034 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-034.

5. 材料 (MATERIAL)

キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>

POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は 53398-***80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***80.



SECT: Y-Y

SECT: X-X

DIMENSION STYLE	SCALE				DESIGN UNITS	THIRD ANGLE PROJECTION
	MM ONLY	---	---	---		
32	33.4	14.95	20.75	17.05	53398-1267	12
24	25.4	9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
		7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
16	17.4	3.7	9.5	5.8	53398-0367	3
		2.45	8.25	4.55	53398-0267	2

CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS
キャリアテープ幅	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER	±0.25
30 OVER	±0.3
ANGULAR	±3°

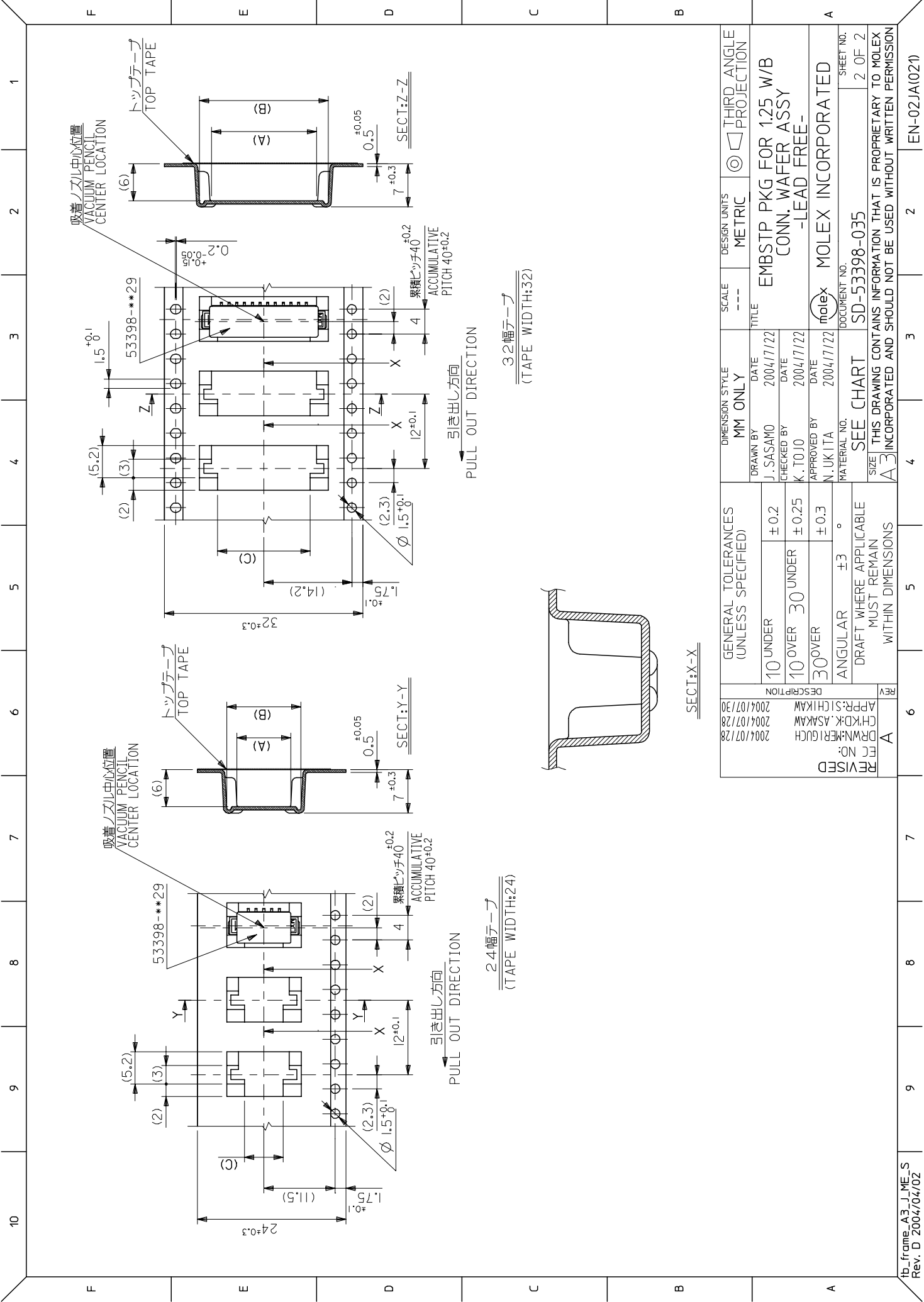
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

REV	DESCRIPTION
A	REVISED
	EC NO.
	DRW: NAKERIGUCHI
	CHK: K. ASAKAWA
	APP: S. ICHIKAWA

DRAWN BY	DATE	TITLE
J. SASAWA	2004/11/22	EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-
CHECKED BY	DATE	
K. TOJO	2004/11/22	
APPROVED BY	DATE	
N. UKITA	2004/11/22	

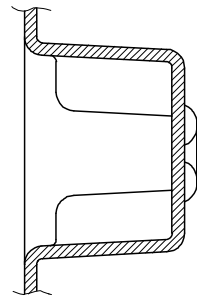
SEE CHART	DOCUMENT NO.	SHEET NO.
SEE CHART	SD-53398-035	1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



2.4幅テープ
(TAPE WIDTH:24)

3.2幅テープ
(TAPE WIDTH:32)



SECT: X-X

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER	± 0.2	DRAWN BY J. SASAMO	DATE 2004/11/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-		
10 OVER	30 UNDER	CHECKED BY K. TOJO	DATE 2004/11/22	DOCUMENT NO. MOLEX INCORPORATED		
30 OVER		APPROVED BY N. UKITA	DATE 2004/11/22	SHEET NO. 2 OF 2		
ANGULAR	± 3 °	MATERIAL NO. SEE CHART		SD-53398-035		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
REVISED	EC NO.	DESCRIPTION		A3 INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
2004/07/28	2004/07/28	DRWN:MERI GUCH	2004/07/28	A3		
2004/07/28	2004/07/28	CHKD:K. ASAKAW	2004/07/28	A3		
2004/07/30	2004/07/30	APPR:SI CHIKAW	2004/07/30	A3		